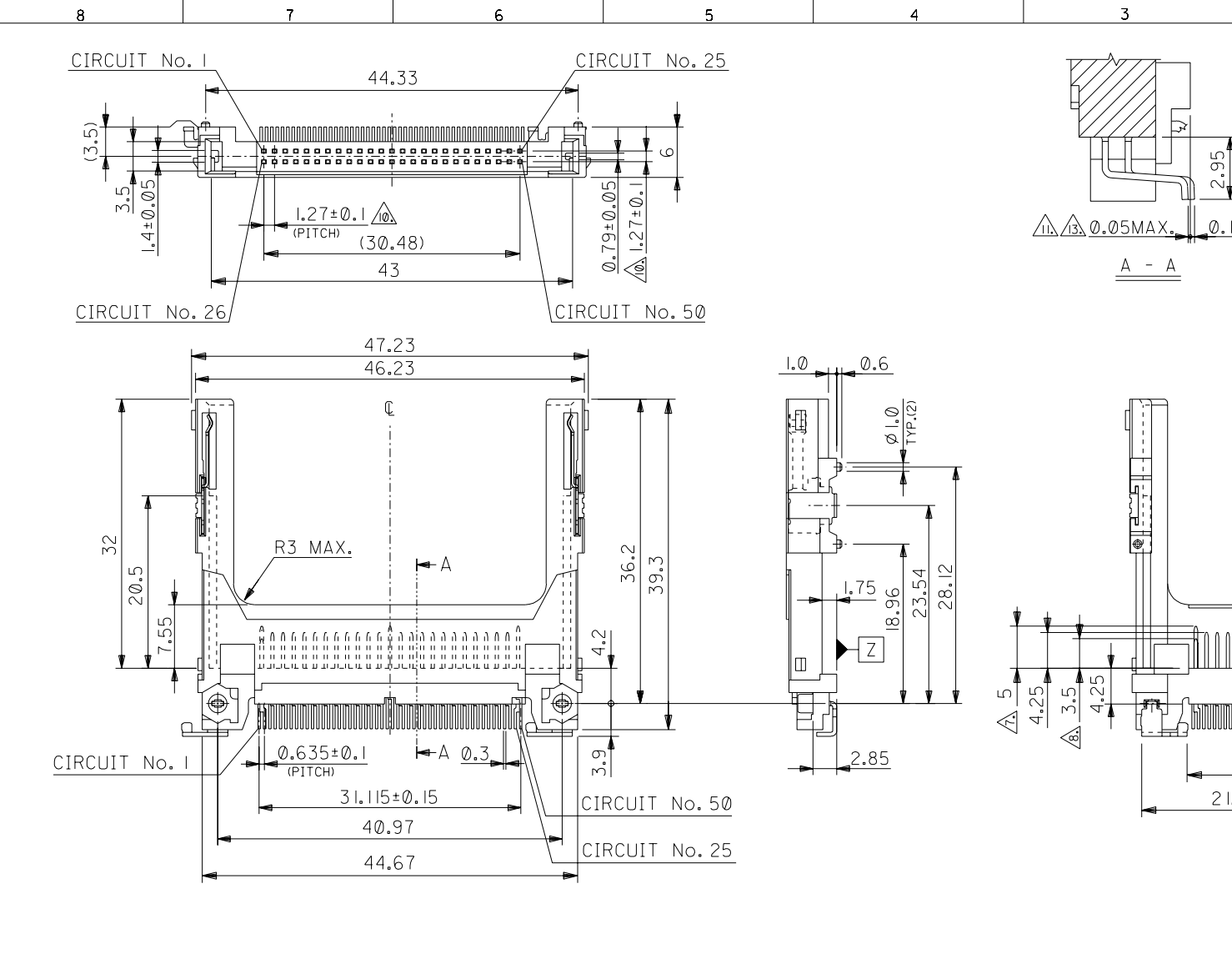


DO NOT SCALE DRAWING



SEMI-HARD TRAY PACKAGE	55359-5027
SOFT TRAY PACKAGE	55359-5029
PACKING TRAY FORM	MATERIAL NO.

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/03/22 EC NO. J2004-3249 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	MATERIAL 材料 SHEET 2 OF 2 参照 REFER TO SHEET 2 OF 2 FINISH 仕上付 SHEET 2 OF 2 参照 REFER TO SHEET 2 OF 2 WIRE RANGE 適用線被範圍 〃〃 INS. RANGE 被覆外径 〃〃	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未滿 ±0.2 10 OVER 30 UNDER 未滿 ±0.25 30 OVER 以上 ±0.3 ANGLE 角度 ±3°	SCALE 〃〃 DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH DRAWN BY & DATE Y. Sakiyama '04/03/22 CHECKED BY & DATE H. Sasaki '04/03/22 APPROVED BY & DATE M. Sasaki '04/03/22 CAD FILENAME SD-55359-015.S01	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY SHT REV REVISION ON CAD ONLY TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, REVERSE) -LEAD FREE- MOLEX INCORPORATED MATERIAL NO. SEE CHART DRAWING NO. SD-55359-015 SHEET NO. 1 OF 2
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THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

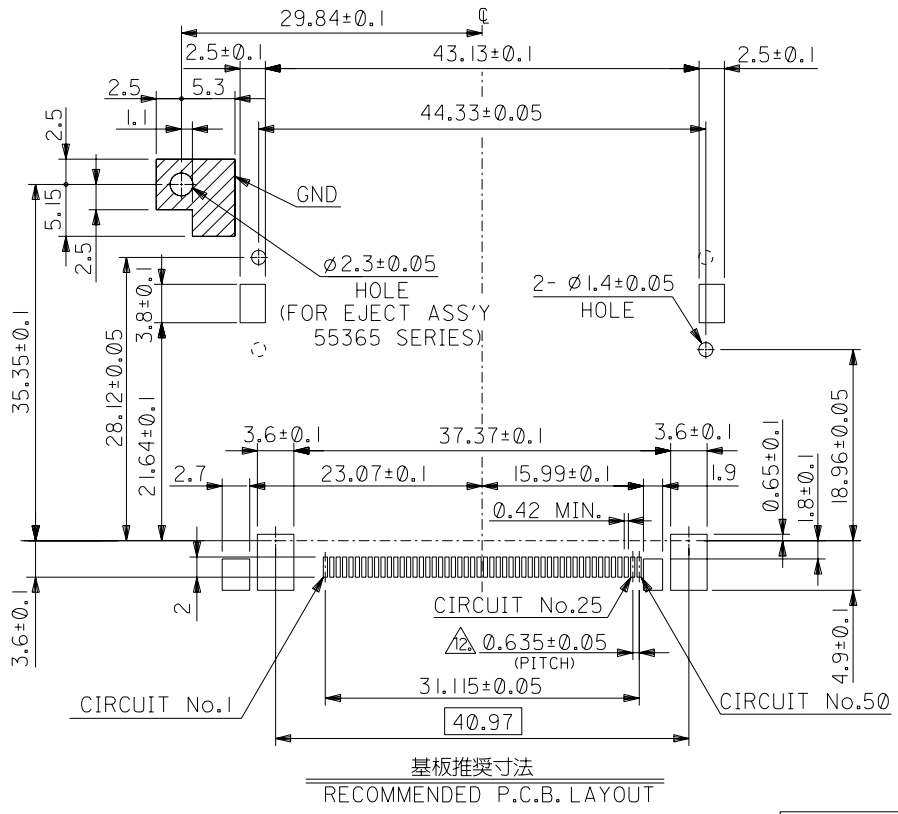
DWG. NO. SD-55359-015

- 注) 1. 材質 MATERIAL
 ハウジング: ガラス入りLCP UL94V-0
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0
 ピン: リン青銅
 PIN: PHOSPHOR BRONZE
 ネール: リン青銅 (t0.3)
 NAIL: PHOSPHOR BRONZE (t0.3)
 リヤネール: リン青銅 (t0.48)
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING
 ピン 接点部: パラジウムニッケル下地、金メッキ
 PIN CONTACT AREA: GOLD OVER PALLADIUM-NICKEL PLATING
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN PLATING
 下地メッキ: ニッケルメッキ
 UNDER PLATING: NICKEL ALL OVER PLATING
- ネール 接点部: 金メッキ
 NAIL CONTACT AREA: GOLD PLATING
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN PLATING
 下地メッキ: ニッケルメッキ
 UNDER PLATING: NICKEL ALL OVER PLATING
- リヤネール 錫メッキ
 REAR-NAIL TIN PLATING
 下地メッキ: ニッケルメッキ
 UNDER PLATING: NICKEL ALL OVER PLATING
3. 推奨基板厚: t=0.8 MIN.
 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚
 RECOMMENDED CARD THICKNESS
 接続部: 3.3±0.1
 CONNECTING AREA: 3.3±0.1
5. 適合カード幅: 42.8±0.1
 RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒
 HOUSING COLOR: BLACK
- △1 寸法適用極: 1,13,38,50
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
- △2 寸法適用極: 25,26
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
- △3 ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
- △4 ピン根元に適用する。
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

- △1 ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且つソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。
 SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDER TAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDER TAILS TIP.
- △2 公差非累積
 NON-CUMULATIVE
- △3 テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.

14. 鉛フリー対応表
 CORRESPONDENCE TABLE OF LEAD FREE

	SEMI-HARD TRAY PKG	SOFT TRAY PKG
半田品 LEAD CONTENT	55359 -5026	55359 -5021
鉛フリー品 LEAD FREE	55359 -5027	55359 -5029



DO NOT SCALE DRAWING

EC NO.		EC NO.		EC NO.		EC NO.		EC NO.		MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	DIMENSIONS:		SHT	REV	
DRWN:	CHK:	DRWN:	CHK:	DRWN:	CHK:	DRWN:	CHK:	DRWN:	CHK:						mm	INCH			mm
										注記参照 SEE NOTES	10 UNDER 未満	±0.2	mm	INCH	<input type="checkbox"/> mm	<input type="checkbox"/> INCH			
										注記参照 SEE NOTES	10 OVER 30 UNDER 未満	±0.25	mm	INCH	<input type="checkbox"/> mm	<input type="checkbox"/> INCH			
										注記参照 SEE NOTES	30 OVER 以上	±0.3	mm	INCH	<input type="checkbox"/> mm	<input type="checkbox"/> INCH			
										WIRE RANGE 適用電線範囲	ANGLE 角度	±3°							
										INS. RANGE 被覆外径									
RELEASED '04/03/22 EC NO. J2004-3249 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO										TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, REVERSE) -LEAD FREE-		MOLEX MOLEX INCORPORATED		MATERIAL NO. SD-55359-015.S02		DRAWING NO. SD-55359-015		SHEET NO. 2 OF 2	
										THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.									